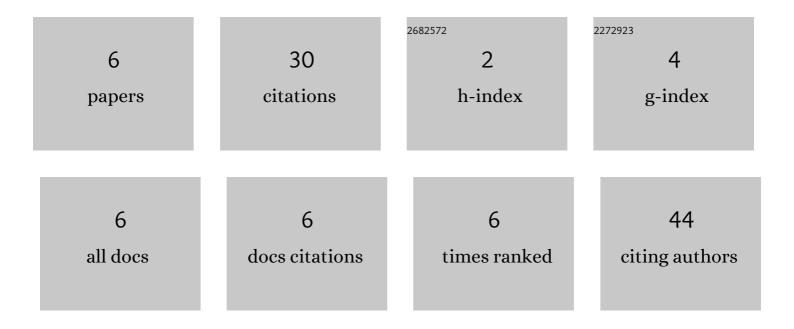


## List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/4137322/publications.pdf Version: 2024-02-01



TENCL

#	Article	IF	CITATIONS
1	Chip Scale 12-Channel 10 Gb/s Optical Transmitter and Receiver Subassemblies Based on Wet Etched Silicon Interposer. Journal of Lightwave Technology, 2017, 35, 3229-3236.	4.6	20
2	Wet-Etched Three-Level Silicon Interposer for 3-D Embedding and Connecting of Optoelectronic Dies and CMOS ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 570-577.	2.5	4
3	A Platform for 2-Dimensional 48-Channel Optical Interconnects Based on Wet Etched Silicon Interposer. , 2017, , .		3
4	48-Channel Matrix Optical Transmitter on a Single Direct Fiber Connector. IEEE Transactions on Electron Devices, 2018, 65, 3816-3822.	3.0	2
5	<inline-formula> <tex-math notation="LaTeX">\$48imes10\$ </tex-math> </inline-formula> -Gb/s Cost-Effective FPC-Based On-Board Optical Transmitter and Receiver. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1353-1362.	2.5	1
6	A 100 Gbps Optical Transceiver Engine by Using Photo-Imageable Thick Film on Ceramics. IEEE Photonics Technology Letters, 2019, 31, 1999-2002.	2.5	0